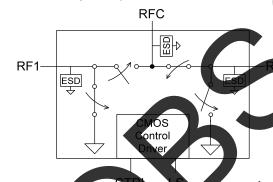


Product Description

The PE42551 RF Switch is designed to support the requirements of the test equipment and ATE market. This broadband general purpose switch maintains excellent RF performance and linearity from 9 kHz through 6000 MHz. The PE42551 integrates on-board CMOS control logic driven by a single-pin, low voltage CMOS control input. It also has a logic select pin which enables changing the logic definition of the control pin. Additional features include a novel user defined logic table, enabled by the on-board CMOS circuitry. The PE42551 also exhibits outstanding isolation that approaches 21 dB at 6000 MHz and is offered in a small 4x4x0.85 mm QFN package.

The PE42551 is manufactured on Peregrine's UltraCMOS® process, a patented variation of silicon-on-insulator (SOI) technology on a sapphire substrate, offering the performance of GaAs with the economy and integration of conventional CMOS.

Figure 1. Functional Diagram
Peregrine Specification 71-0065



Product Specification

PE42551

SPDT UltraCMOS® RF Switch 9 kHz - 6000 MHz

Features

- HaRP™-Technology –Enhanced
 - Eliminates Gate and Phase Lag
 - No insertion loss nor phase drift
 - Fast settling time
- High linearity 50 dBm IIP3
- Low insertion loss: 0.65 dB at 3000 MHz, 0.90 dB at 6000 MHz
- High isolation of 29 dB at 3000 MHz,
 21 dB at 6000 MHz
- High power NaB compression point of +34 dBm
- ESD: 500 V HBM
- Single-pin 2.75 CMOS logic control
- Logic select pin to enange definition of logic control
- Reflective switch design
- 20-lead 4x4x0.85 mm QFN package

Figure 2. Package Type

20-lead 4x4x0.85 mm QFN



Table 1. Electrical Specifications @ $+25^{\circ}$ C, $y_{DD} = 2.75V$ ($z_s = z_L = 50 \Omega$)

Parameter	Conditions	Min	Typical	Max	Units
Operation Frequency		9 kHz		6000	MHz
Insertion Loss	9 kHz 3000 kHz 6000 MHz		0.55 0.65 0.90	0.65 0.75	dB dB dB
Isolation – RF1 to RF2	8000 MHz 6000 MHz	28	29 21		dB dB
Return Loss RF1, RF2 and RF	3000 MHz 6000 MHz	14	18 14		dB dB
Switching Time	50% CTRL to 0.1 dB final value		7		μs
Input 1 dB Compression	6000 MHz	32	34		dBm
Input IP3	6000 MHz		+50		dBm

Note: Device linearity will begin to degrade below 10 MHz.

Document No. 70-0350-02 | www.psemi.com

©2010-2012 Peregrine Semiconductor Corp. All rights reserved.



Figure 3. Pin Configuration (Top View)

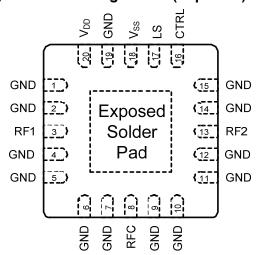


Table 2. Pin Descriptions

Pin No.	Pin Name	Description
13	RF2	RF2 port. ¹
1, 2, 4, 5, 6, 7, 9, 10, 11, 12, 14, 15, 19	GND	Ground Connection. Traces should be physically short and connected to the ground plane. This pin is connected to the exposed solder pad that also must be soldered to the ground plane for best performance.
3	RF1	RF1 port. ¹
16	CTRL	CMOS level (See Table 5)
8	RFC	Common RF port for switch ¹
17	LS	Logic Select - Used to determine the definition for the CTRL pin (see Table 5)
18	V _{S8}	Negative power supply Apply nothinal -2.75V supply ²
20	√ _{DD}	Nominal 2.75V supply connection
Paddle	GND	Exposed Ground Paddle

1. All RF VDC or the DC must be Notes: must be held at an external capacito

2. Use V_{SS} (pir nternal negative n) to bypass an voltage generator. Connect V_{SS} (pin s = 0V) to enable internal negative voltage generator.

Table 3. Absolute Maximum Ratings

Symbol	Parameter/Conditions	Min	Max	Units
V_{DD}	Power supply voltage	-0.3	4.0	٧
Vı	Voltage on any input except for CTRL and LS inputs	-0.3	V _{DD} + 0.3	V
V _{CTRL}	Voltage on CTRL input		4.0	V
V _{LS}	Voltage on LS input		4.0	V
T _{ST}	Storage temperature range	-65	150	°C
T _{OP}	Operating temperature range	-40	85	°C
P _{IN}	Input Power 50Ω: 9 kHz ≤ 4 MHz 4 MHz ≤ 6 GHz		Fig. 4 31	dBm dBm
V _{ESD}	ESD voltage HBM		500	٧

nan Body Model (HBM, MIL_STD 883 Method 3015.7

eding absolute maximum ratings mav cause permanent damage. Operation should be restricted to the limits in the Operating Ranges table. Operation between operating range maximum and absolute maximum for extended seriods may reduce reliability.

Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS® device, observe the same precautions that you would use with other SD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid xceeding the rating specified.

Moisture Sensitivity Level

The Moisture Sensitivity Level rating for the PE42551 in the 20-lead 4x4x0.85 mm QFN package is MSL1.

Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS® devices are immune to latch-up.

cked with



Table 4. Operating Specifications

Parameter	Min	Тур	Max	Units
V _{DD} Positive Power Supply Voltage	2.5	2.75	3.0	V
V _{DD} Negative Power Supply Voltage	-2.5	-2.75	-3.0	٧
I _{DD} Power Supply Current (V _{DD} = 3V, V _{CNTL} = 3V)		20		μΑ
Control Voltage High	$0.7xV_{DD}$			V
Control Voltage Low			0.3xV _{DD}	V
RF Power In 50Ω: 9 kHz \leq 4 MHz 4 MHz \leq 6 GHz			Fig. 4 31	dBm dBm

Spurious Performance

The typical spurious performance of the PE42551 is -116 dBm when $V_{SS} = 0V$. If further improvement is desired, the internal negative voltage generator can be disabled by externally applying a negative voltage to the V_{SS} pin such that $V_{SS} = -V_{DD}$.

Table 5. Control Logic Truth Table

LS	CTRL	RFC-RF1	RFC-RF2
0	0	off	on
0	1	on	off
1	0	øn	off
1	1	off	on

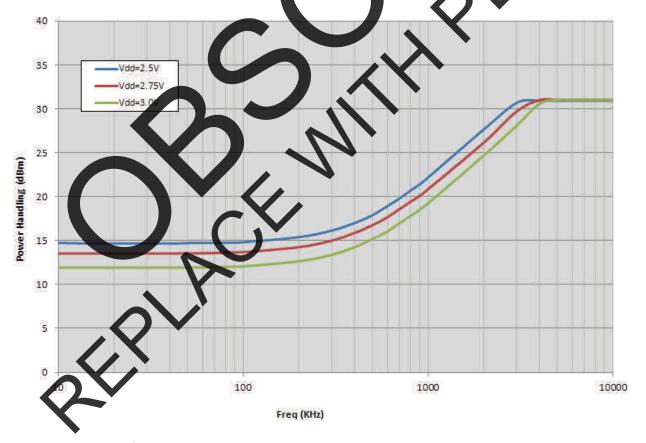
Logic Select (LS)

The Logic Select leature is use etermine the definition for the CTRL pin.

Switching Frequency

The PE42551 has a maximum 2 the internal negative voltage generator is used. In the event a customer applies V_{SS} external (-VDE to Pin 18, the Switching Rate is limited to the reciprocal of he Switching Time in able 1

Figure 4. Power Handling vs Frequency a d Vdd



Document No. 70-0350-02 | www.psemi.com



Evaluation Kit

The SPDT Switch Evaluation Kit board was designed to ease customer evaluation of the PE42551 SPDT switch. The RF common port is connected through a 50 Ω transmission line to J2. Port 1 and Port 2 are connected through 50 Ω transmission lines to J1 and J3. A through transmission line connects SMA connectors J4 and J5. This transmission line can be used to estimate the loss of the PCB over the environmental conditions being evaluated.

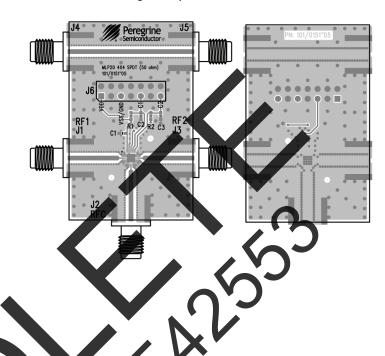
The board is constructed of a two metal layer FR4 material with a total thickness of 0.032". The transmission lines were designed using a coplanar waveguide with ground plane (28 mil core, 47.6 mil width, 30 mil gap).

Good RF layout and prudent use of vias is critical for obtaining the specified isolation performance for the device shown in this datasheet.

J6 provides a means for controlling DC and digital inputs to the device. The provided jump short the package pin to ground for logic low When the jumper is removed, the pin is pulled to V_{DD} for logic high. When the jumper is in pla 3 μA of current will flow through the 11/10 resistor. This extra current should not be

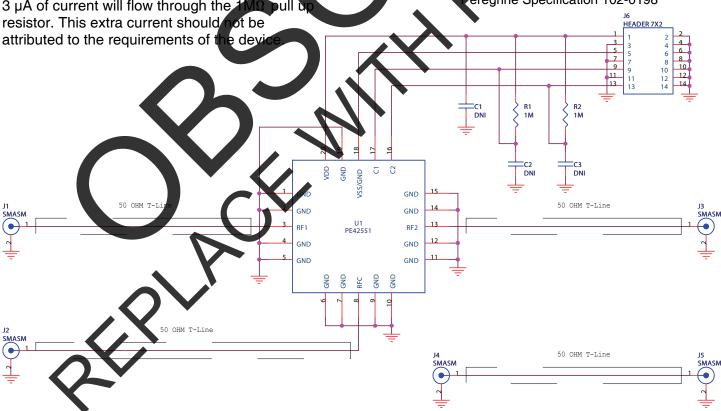
Figure 5. Evaluation Board Layouts

Peregrine Specification 101-0151



igure 6. Ev on Board Schematic

eregrine Specification 102-0198





Typical Performance Data

Figure 7. Insertion Loss: RFC-RF1@ 25°C

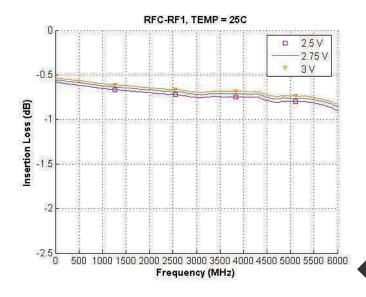


Figure 8. Insertion Loss: RFC-RF1@ 2.75V

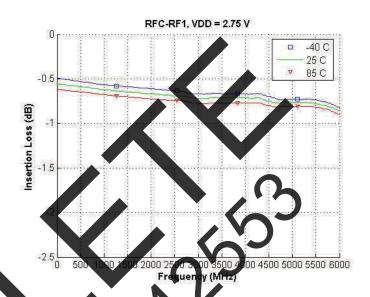


Figure 9. Insertion Loss: RFC-RF2 @ 25°Q

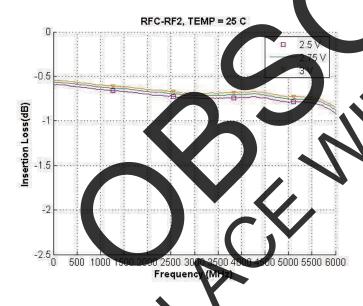
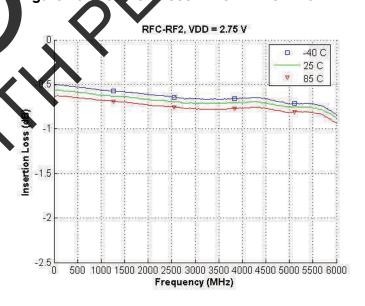


Figure 10. Ins ertion Loss: RFC-RF2 @ 2.75V



©2010-2012 Peregrine Semiconductor Corp. All rights reserved.

Document No. 70-0350-02 | UltraCMOS® RFIC Solutions



Typical Performance Data

Figure 11. Isolation: RFC-RF1@ 25°C

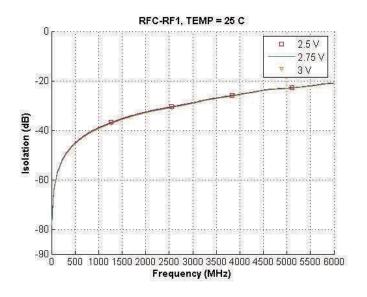


Figure 12. Isolation: RFC-RF1@ 2.75V

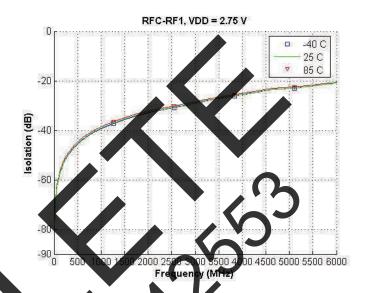


Figure 13. Isolation: RFC-RF2 @ 25°C

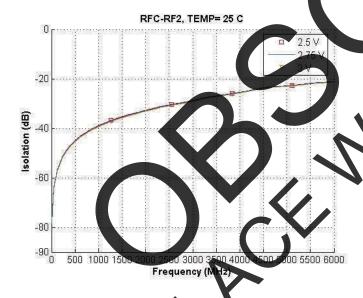
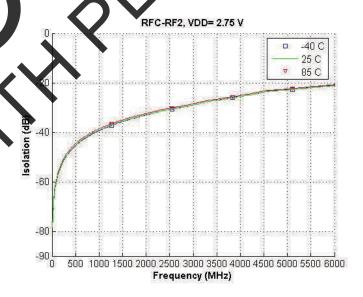


Figure 14. Isolation: RFC-RF2 @ 2.75V





Typical Performance Data

Figure 15. Return Loss: RF1 @ 25°C (RFC-RF1 Active Path)

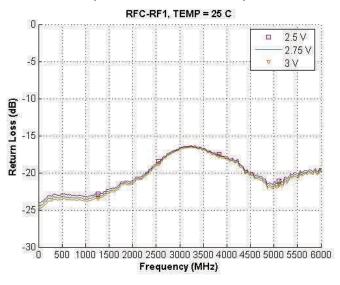


Figure 16. Return Loss: RF1 @ 2.75V (RFC-RF1 Active Path)

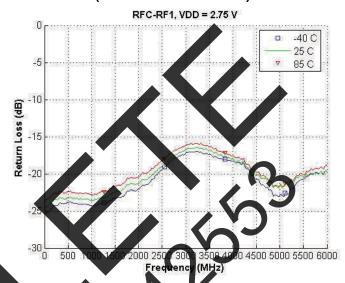
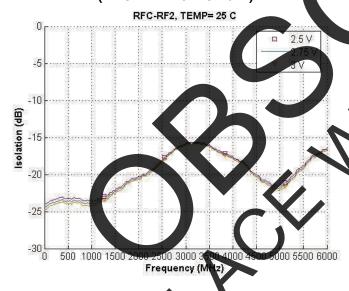
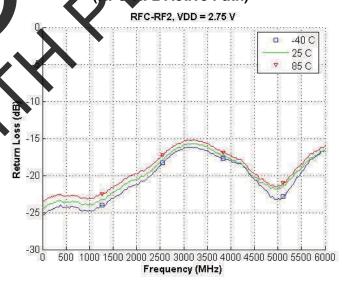


Figure 17. Return Loss: RF2 @ 25°C (RFC-RF2 Active Path)



igure 18. oss: RF2 @ 2.75V -BF2 Active Path)



©2010-2012 Peregrine Semiconductor Corp. All rights reserved.

Document No. 70-0350-02 | UltraCMOS® RFIC Solutions



Figure 19. Package Drawing

20-lead 4x4x0.85 mm QFN Peregrine Specification 19-0106

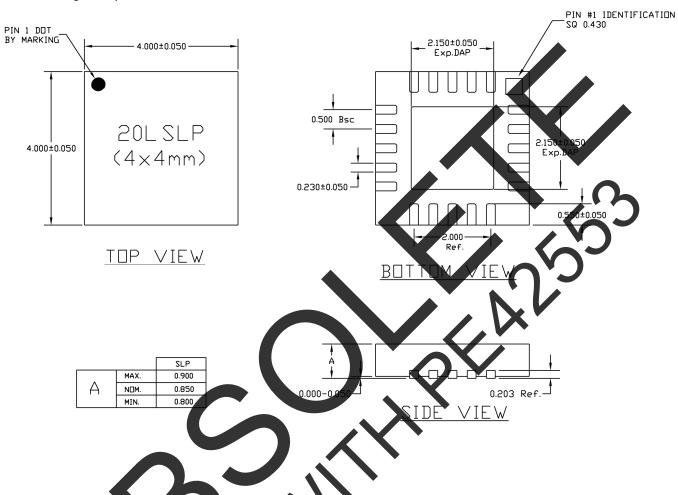
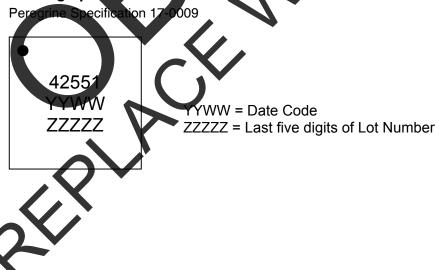


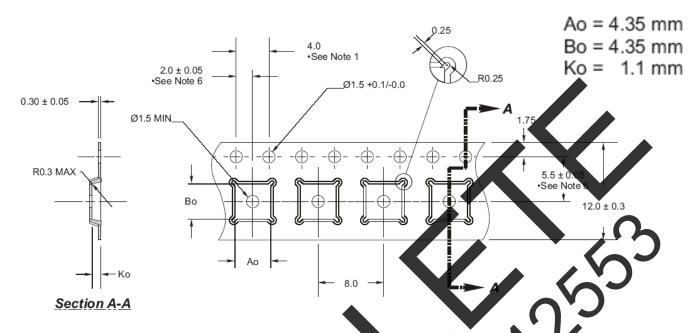
Figure 20. Marking Specifications



Document No. 70-0350-02 | www.psemi.com



Figure 21. Tape and Reel Drawing



Notes:

- 1. 10 sprocket hole pitch cumulative tolerance ±
- 2. Camber not to exceed 1mm in 100mm.
- 3. Material: PS + C.
- 4. Ao and Bo measured as indicated.
- 5. Ko measured from a plane on the the pocket to the top surface of the rrier.
- 6. Pocket position relative to sprocl true position of pocket, not pocket h

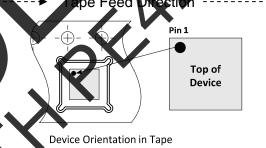


Table 6. Ordering Informat

Order Code	Part Marking	Description	Package	Shipping Method
42551-00	PE42551\EK	PE 2551 20QFN 4x4 mm-EK	Evaluation Kit	1/Box
42551-51	42551	PE425510 20QFN 4x4 mm	Green 20-lead 4x4 mm QFN	Cut Tape
42551-52	42551	PE4255 G-20QFN 4x4 mm-3000C	Green 20-lead 4x4 mm QFN	3000 units/T&R

Sales Contact and Informatio

For sales and contact information please visit www.psemi.com.

Advance Information: The rmative or design stage. The datasheet contains design target specifications for product ations and features may change in any manner without notice. ntains preliminary data. Additional data may be added at a later Preliminary Specification pecifications at any time without notice in order to supply the best date. Peregrine res possible product. The datasheet contains final data. In the event Peregrine decides to notify customers of the intended changes by issuing a CNF (Customer change the spe Notification For

atasheet is believed to be reliable. However, Peregrine assumes no liability for the use hall be entirely at the user's own risk. The information in

No patent rights or licenses to any circuits described in this datasheet are implied or granted to any third party. Peregrine's products are not designed or intended for use in devices or systems intended for surgical implant. or in other applications intended to support or sustain life, or in any application in which the failure of the Peregrine product could create a situation in which personal injury or death might occur. Peregrine assumes no liability for damages, including consequential or incidental damages, arising out of the use of its products in such applications.

The Peregrine name, logo, UltraCMOS and UTSi are registered trademarks and HaRP, MultiSwitch and DuNE are trademarks of Peregrine Semiconductor Corp.

Document No. 70-0350-02 | UltraCMOS® RFIC Solutions